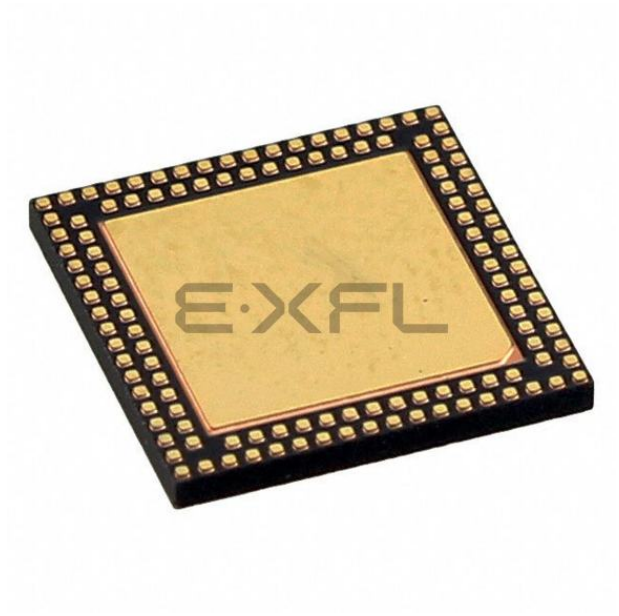

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Details	
Product Status	Obsolete
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	85
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	16K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 28x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	124-VFTLA Dual Rows, Exposed Pad
Supplier Device Package	124-VTLA (9x9)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx430f064l-v-tl

TABLE 4: PIN NAMES FOR 100-PIN DEVICES (CONTINUED)

100-PIN TQFP (TOP VIEW)(1,2,3)

PIC32MX330F064L
PIC32MX350F128L
PIC32MX350F256L
PIC32MX370F512L

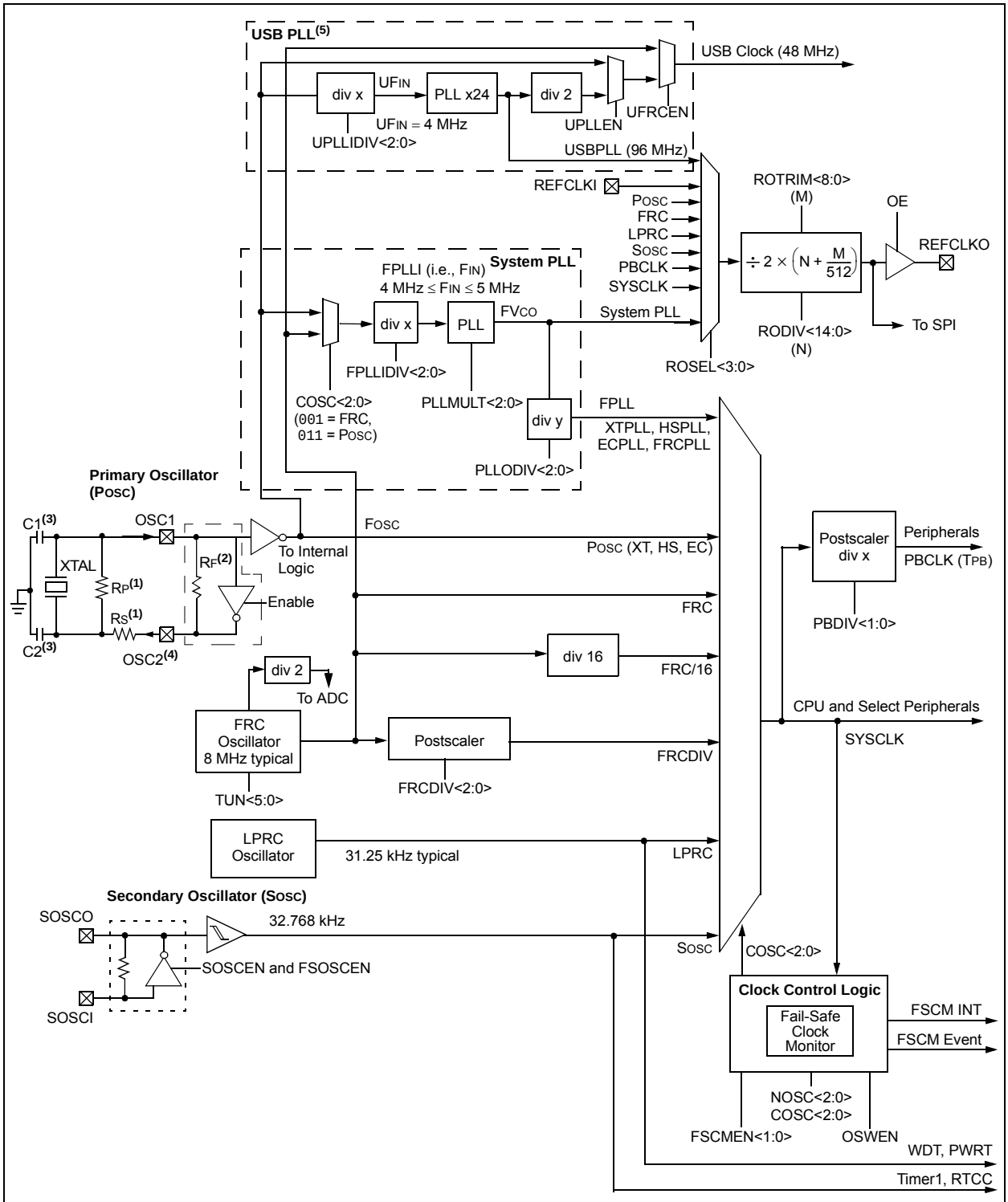
Pin #	Full Pin Name	Pin #	Full Pin Name
71	RPD11/PMCS1/RD11	86	VDD
72	RPD0/RD0	87	RPF0/PMD11/RF0
73	SOSCI/RPC13/RC13	88	RPF1/PMD10/RF1
74	SOSCO/RPC14/T1CK/RC14	89	RPG1/PMD9/RG1
75	VSS	90	RPG0/PMD8/RG0
76	AN24/RPD1/RD1	91	TRCLK/RA6
77	AN25/RPD2/RD2	92	TRD3/CTED8/RA7
78	AN26/RPD3/RD3	93	PMD0/RE0
79	RPD12/PMD12/RD12	94	PMD1/RE1
80	PMD13/RD13	95	TRD2/RG14
81	RPD4/PMWR/RD4	96	TRD1/RG12
82	RPD5/PMRD/RD5	97	TRD0/RG13
83	PMD14/RD6	98	AN20/PMD2/RE2
84	PMD15/RD7	99	RPE3/CTPLS/PMD3/RE3
85	VCAP	100	AN21/PMD4/RE4

Note 1: The RPn pins can be used by remappable peripherals. See Table 1 for the available peripherals and **Section 12.3 "Peripheral Pin Select"** for restrictions.

2: Every I/O port pin (RAx-RGx), with the exception of RF6, can be used as a change notification pin (CNAx-CNGx). See **Section 12.0 "I/O Ports"** for more information.

3: RPF6 (pin 55) and RPF7 (pin 54) are only remappable for input functions.

FIGURE 8-1: PIC32MX330/350/370/430/450/470 FAMILY CLOCK DIAGRAM



Notes:
1. A series resistor, RS, may be required for AT strip cut crystals or eliminate clipping. Alternately, to increase oscillator circuit gain, add a parallel resistor, RP, with a value of 1 MΩ.
2. The internal feedback resistor, RF, is typically in the range of 2 MΩ to 10 MΩ.
3. Refer to **Section 6. "Oscillator Configuration"** (DS60001112) in the "*PIC32 Family Reference Manual*" for help in determining the best oscillator components.
4. PBCLK out is available on the OSC2 pin in certain clock modes.
5. USB PLL is available on PIC32MX4XX devices only.

9.0 PREFETCH CACHE

Note: This data sheet summarizes the features of the PIC32MX330/350/370/430/450/470 family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 4. "Prefetch Cache"** (DS60001119), which is available from the *Documentation > Reference Manual* section of the Microchip PIC32 web site (www.microchip.com/pic32).

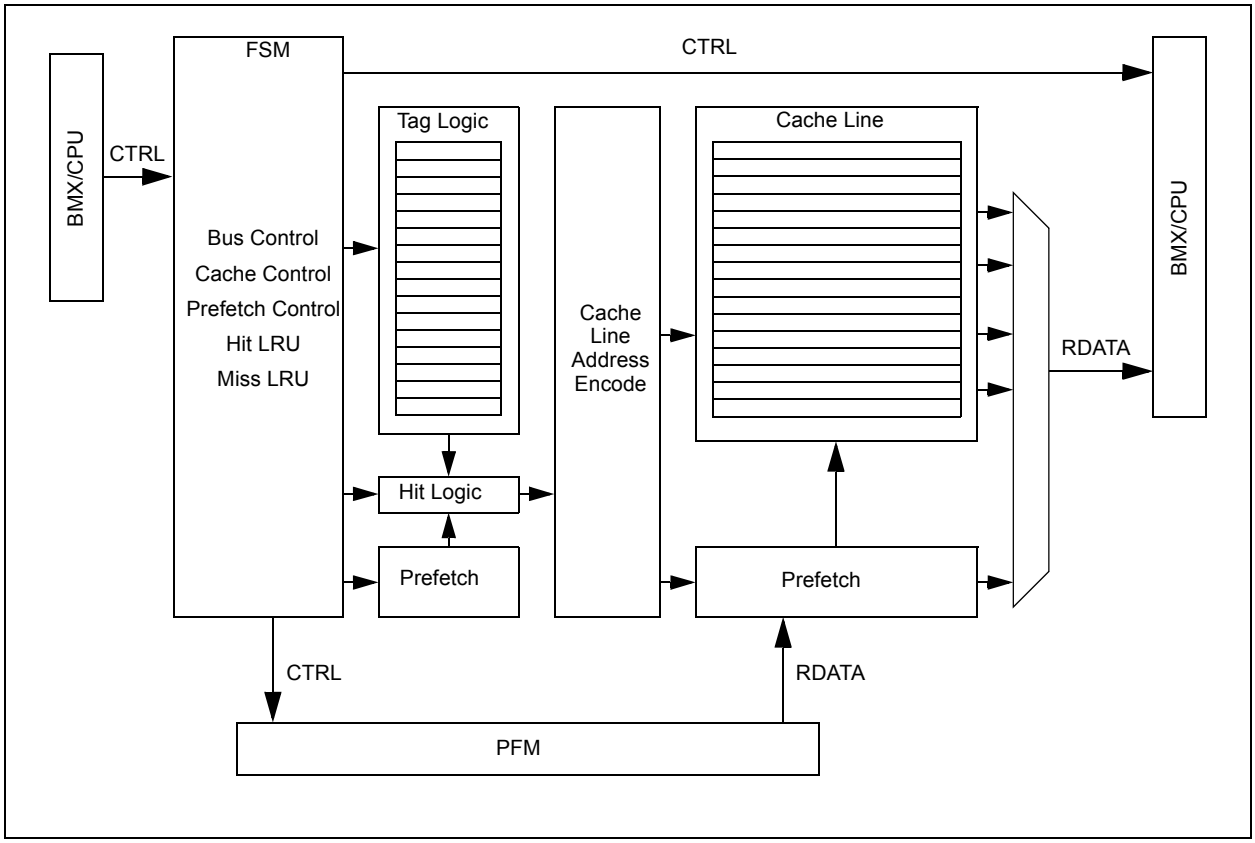
Prefetch cache increases performance for applications executing out of the cacheable program Flash memory regions by implementing instruction caching, constant data caching and instruction prefetching.

9.1 Features

- 16 fully associative lockable cache lines
- 16-byte cache lines
- Up to four cache lines allocated to data
- Two cache lines with address mask to hold repeated instructions
- Pseudo LRU replacement policy
- All cache lines are software writable
- 16-byte parallel memory fetch
- Predictive instruction prefetch

A simplified block diagram of the Prefetch Cache module is illustrated in Figure 9-1.

FIGURE 9-1: PREFETCH CACHE MODULE BLOCK DIAGRAM



REGISTER 9-1: CHECON: CACHE CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0
	—	—	—	—	—	—	—	CHECOH
15:8	U-0	U-0	U-0	U-0	U-0	U-0	R/W-0	R/W-0
	—	—	—	—	—	—	DCSZ<1:0>	
7:0	U-0	U-0	R/W-0	R/W-0	U-0	R/W-1	R/W-1	R/W-1
	—	—	PREFEN<1:0>		—	PFMWS<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-17 **Unimplemented:** Write '0'; ignore read

bit 16 **CHECOH:** Cache Coherency Setting on a PFM Program Cycle bit
- 1 = Invalidate all data and instruction lines
- 0 = Invalidate all data lnes and instruction lines that are not locked

bit 15-10 **Unimplemented:** Write '0'; ignore read

bit 9-8 **DCSZ<1:0>:** Data Cache Size in Lines bits
- 11 = Enable data caching with a size of 4 Lines
- 10 = Enable data caching with a size of 2 Lines
- 01 = Enable data caching with a size of 1 Line
- 00 = Disable data caching

Changing these bits induce all lines to be reinitialized to the "invalid" state.

bit 7-6 **Unimplemented:** Write '0'; ignore read

bit 5-4 **PREFEN<1:0>:** Predictive Prefetch Enable bits
- 11 = Enable predictive prefetch for both cacheable and non-cacheable regions
- 10 = Enable predictive prefetch for non-cacheable regions only
- 01 = Enable predictive prefetch for cacheable regions only
- 00 = Disable predictive prefetch

bit 3 **Unimplemented:** Write '0'; ignore read

bit 2-0 **PFMWS<2:0>:** PFM Access Time Defined in Terms of SYSLK Wait States bits
- 111 = Seven Wait states
- 110 = Six Wait states
- 101 = Five Wait states
- 100 = Four Wait states
- 011 = Three Wait states
- 010 = Two Wait states
- 001 = One Wait state
- 000 = Zero Wait state

REGISTER 10-8: DCHxECON: DMA CHANNEL 'x' EVENT CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHAIRQ<7:0>(1)							
15:8	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1	R/W-1
	CHSIRQ<7:0>(1)							
7:0	S-0	S-0	R/W-0	R/W-0	R/W-0	U-0	U-0	U-0
	CFORCE	CABORT	PATEN	SIRQEN	AIRQEN	—	—	—

Legend:	S = Settable bit		
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-24 **Unimplemented:** Read as '0'

bit 23-16 **CHAIRQ<7:0>:** Channel Transfer Abort IRQ bits(1)
- 11111111 = Interrupt 255 will abort any transfers in progress and set CHAIF flag
- •
- •
- •
- 00000001 = Interrupt 1 will abort any transfers in progress and set CHAIF flag
- 00000000 = Interrupt 0 will abort any transfers in progress and set CHAIF flag

bit 15-8 **CHSIRQ<7:0>:** Channel Transfer Start IRQ bits(1)
- 11111111 = Interrupt 255 will initiate a DMA transfer
- •
- •
- •
- 00000001 = Interrupt 1 will initiate a DMA transfer
- 00000000 = Interrupt 0 will initiate a DMA transfer

bit 7 **CFORCE:** DMA Forced Transfer bit
- 1 = A DMA transfer is forced to begin when this bit is written to a '1'
- 0 = This bit always reads '0'

bit 6 **CABORT:** DMA Abort Transfer bit
- 1 = A DMA transfer is aborted when this bit is written to a '1'
- 0 = This bit always reads '0'

bit 5 **PATEN:** Channel Pattern Match Abort Enable bit
- 1 = Abort transfer and clear CHEN on pattern match
- 0 = Pattern match is disabled

bit 4 **SIRQEN:** Channel Start IRQ Enable bit
- 1 = Start channel cell transfer if an interrupt matching CHSIRQ occurs
- 0 = Interrupt number CHSIRQ is ignored and does not start a transfer

bit 3 **AIRQEN:** Channel Abort IRQ Enable bit
- 1 = Channel transfer is aborted if an interrupt matching CHAIRQ occurs
- 0 = Interrupt number CHAIRQ is ignored and does not terminate a transfer

bit 2-0 **Unimplemented:** Read as '0'

Note 1: See **Table 7-1: "Interrupt IRQ, Vector and Bit Location"** for the list of available interrupt IRQ sources.

TABLE 11-1: USB REGISTER MAP (CONTINUED)

Virtual Address (BF88_#)	Register Name(1)	Bit Range	Bits															All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
5390	U1EP9	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53A0	U1EP10	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53B0	U1EP11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53C0	U1EP12	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53D0	U1EP13	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53E0	U1EP14	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000
53F0	U1EP15	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	EPCONDIS	EPRXEN	EPTXEN	EPSTALL	EPHSHK	0000

Legend: x = unknown value on Reset; — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: With the exception of those noted, all registers in this table (except as noted) have corresponding CLR, SET and INV registers at its virtual address, plus an offset of 0x4, 0x8 and 0xC respectively. See **Section 12.2 "CLR, SET, and INV Registers"** for more information.

2: This register does not have associated SET and INV registers.

3: This register does not have associated CLR, SET and INV registers.

4: Reset value for this bit is undefined.

TABLE 12-1: INPUT PIN SELECTION

Peripheral Pin	[*pin name*]R SFR	[*pin name*]R bits	[*pin name*]R Value to RPn Pin Selection
INT3	INT3R	INT3R<3:0>	0000 = RPD2 0001 = RPG8 0010 = RPF4 0011 = RPD10 0100 = RPF1 0101 = RPB9 0110 = RPB10 0111 = RPC14 1000 = RPB5 1001 = Reserved 1010 = RPC1(3) 1011 = RPD14(3) 1100 = RPG1(3) 1101 = RPA14(3) 1110 = Reserved 1111 = RPF2(1)
T2CK	T2CKR	T2CKR<3:0>	
IC3	IC3R	IC3R<3:0>	
U1RX	U1RXR	U1RXR<3:0>	
U2RX	U2RXR	U2RXR<3:0>	
$\overline{\text{U5CTS}}$	U5CTSR(3)	U5CTSR<3:0>	
REFCLKI	REFCLKIR	REFCLKIR<3:0>	
INT4	INT4R	INT4R<3:0>	0000 = RPD3 0001 = RPG7 0010 = RPF5 0011 = RPD11 0100 = RPF0 0101 = RPB1 0110 = RPE5 0111 = RPC13 1000 = RPB3 1001 = Reserved 1010 = RPC4(3) 1011 = RPD15(3) 1100 = RPG0(3) 1101 = RPA15(3) 1110 = RPF2(1) 1111 = RPF7(2)
T5CK	T5CKR	T5CKR<3:0>	
IC4	IC4R	IC4R<3:0>	
U3RX	U3RXR	U3RXR<3:0>	
$\overline{\text{U4CTS}}$	U4CTSR	U4CTSR<3:0>	
SDI1	SDI1R	SDI1R<3:0>	
SDI2	SDI2R	SDI2R<3:0>	
INT2	INT2R	INT2R<3:0>	0000 = RPD9 0001 = RPG6 0010 = RPB8 0011 = RPB15 0100 = RPD4 0101 = RPB0 0110 = RPE3 0111 = RPB7 1000 = Reserved 1001 = RPF12(3) 1010 = RPD12(3) 1011 = RPF8(3) 1100 = RPC3(3) 1101 = RPE9(3) 1110 = Reserved 1111 = RPB2
T4CK	T4CKR	T4CKR<3:0>	
IC2	IC2R	IC2R<3:0>	
IC5	IC5R	IC5R<3:0>	
$\overline{\text{U1CTS}}$	U1CTSR	U1CTSR<3:0>	
$\overline{\text{U2CTS}}$	U2CTSR	U2CTSR<3:0>	
$\overline{\text{SS1}}$	SS1R	SS1R<3:0>	

Note 1: This selection is not available on 64-pin USB devices.

2: This selection is only available on 100-pin General Purpose devices.

3: This selection is not available on 64-pin USB and General Purpose devices.

4: This selection is only available on General Purpose devices.

NOTES:

REGISTER 17-1: OCxCON: OUTPUT COMPARE 'x' CONTROL REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
23:16	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—
15:8	R/W-0	U-0	R/W-0	U-0	U-0	U-0	U-0	U-0
	ON(1)	—	SIDL	—	—	—	—	—
7:0	U-0	U-0	R/W-0	R-0	R/W-0	R/W-0	R/W-0	R/W-0
	—	—	OC32	OCFLT(2)	OCTSEL	OCM<2:0>		

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-16 **Unimplemented:** Read as '0'

bit 15 **ON:** Output Compare Peripheral On bit(1)
- 1 = Output Compare peripheral is enabled
- 0 = Output Compare peripheral is disabled

bit 14 **Unimplemented:** Read as '0'

bit 13 **SIDL:** Stop in Idle Mode bit
- 1 = Discontinue operation when CPU enters Idle mode
- 0 = Continue operation in Idle mode

bit 12-6 **Unimplemented:** Read as '0'

bit 5 **OC32:** 32-bit Compare Mode bit
- 1 = OCxR<31:0> and/or OCxRS<31:0> are used for comparisions to the 32-bit timer source
- 0 = OCxR<15:0> and OCxRS<15:0> are used for comparisons to the 16-bit timer source

bit 4 **OCFLT:** PWM Fault Condition Status bit(2)
- 1 = PWM Fault condition has occurred (cleared in HW only)
- 0 = No PWM Fault condition has occurred

bit 3 **OCTSEL:** Output Compare Timer Select bit
- 1 = Timer3 is the clock source for this Output Compare module
- 0 = Timer2 is the clock source for this Output Compare module

bit 2-0 **OCM<2:0>:** Output Compare Mode Select bits
- 111 = PWM mode on OCx; Fault pin is enabled
- 110 = PWM mode on OCx; Fault pin is disabled
- 101 = Initialize OCx pin low; generate continuous output pulses on OCx pin
- 100 = Initialize OCx pin low; generate single output pulse on OCx pin
- 011 = Compare event toggles OCx pin
- 010 = Initialize OCx pin high; compare event forces OCx pin low
- 001 = Initialize OCx pin low; compare event forces OCx pin high
- 000 = Output compare peripheral is disabled but continues to draw current

Note 1: When using the 1:1 PBCLK divisor, the user software should not read/write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit is only used when OCM<2:0> = '111'. It is read as '0' in all other modes.

REGISTER 18-1: SPIxCON: SPI CONTROL REGISTER (CONTINUED)

bit 4 **DISSDI:** Disable SDI bit
1 = SDI pin is not used by the SPI module (pin is controlled by PORT function)
0 = SDI pin is controlled by the SPI module

bit 3-2 **STXISEL<1:0>:** SPI Transmit Buffer Empty Interrupt Mode bits
11 = Interrupt is generated when the buffer is not full (has one or more empty elements)
10 = Interrupt is generated when the buffer is empty by one-half or more
01 = Interrupt is generated when the buffer is completely empty
00 = Interrupt is generated when the last transfer is shifted out of SPISR and transmit operations are complete

bit 1-0 **SRXISEL<1:0>:** SPI Receive Buffer Full Interrupt Mode bits
11 = Interrupt is generated when the buffer is full
10 = Interrupt is generated when the buffer is full by one-half or more
01 = Interrupt is generated when the buffer is not empty
00 = Interrupt is generated when the last word in the receive buffer is read (i.e., buffer is empty)

Note 1: When using the 1:1 PBCLK divisor, the user software should not read or write the peripheral's SFRs in the SYSCLK cycle immediately following the instruction that clears the module's ON bit.

2: This bit can only be written when the ON bit = 0.

3: This bit is not used in the Framed SPI mode. The user should program this bit to '0' for the Framed SPI mode (FRMEN = 1).

4: When AUDEN = 1, the SPI module functions as if the CKP bit is equal to '1', regardless of the actual value of CKP.

20.2 Timing Diagrams

Figure 20-2 and Figure 20-3 illustrate typical receive and transmit timing for the UART module.

FIGURE 20-2: UART RECEPTION

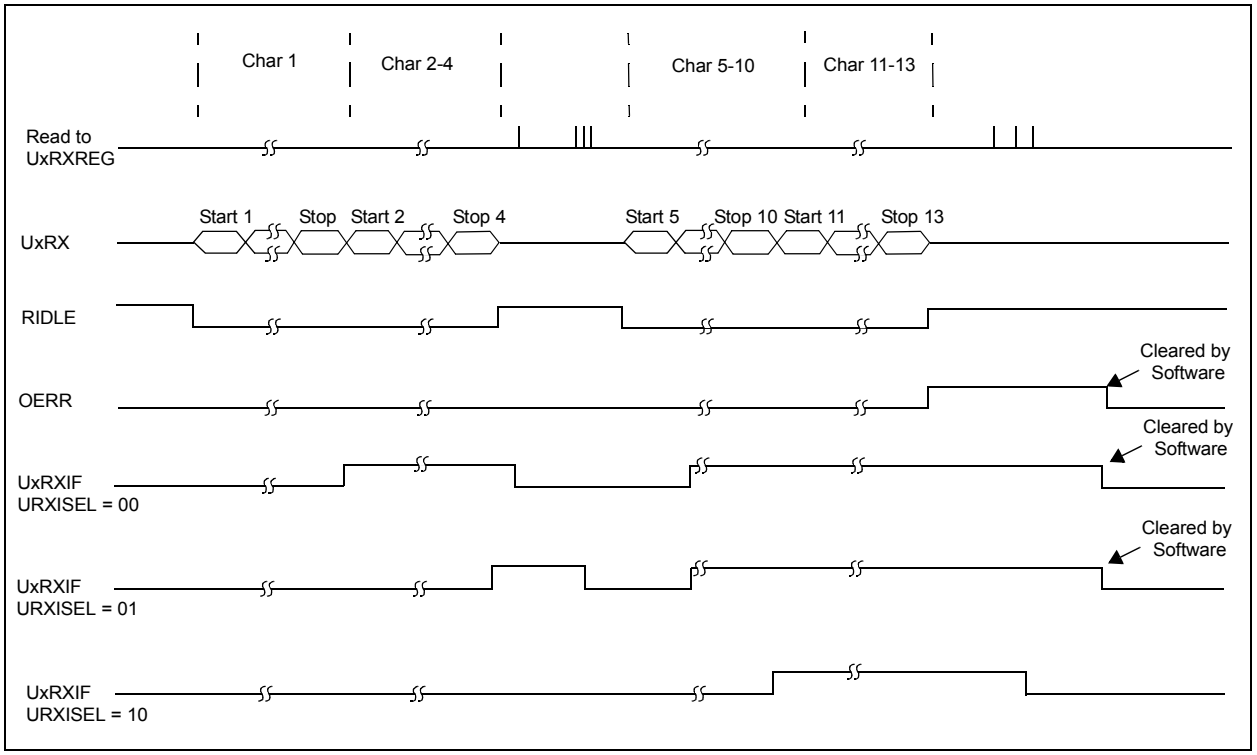
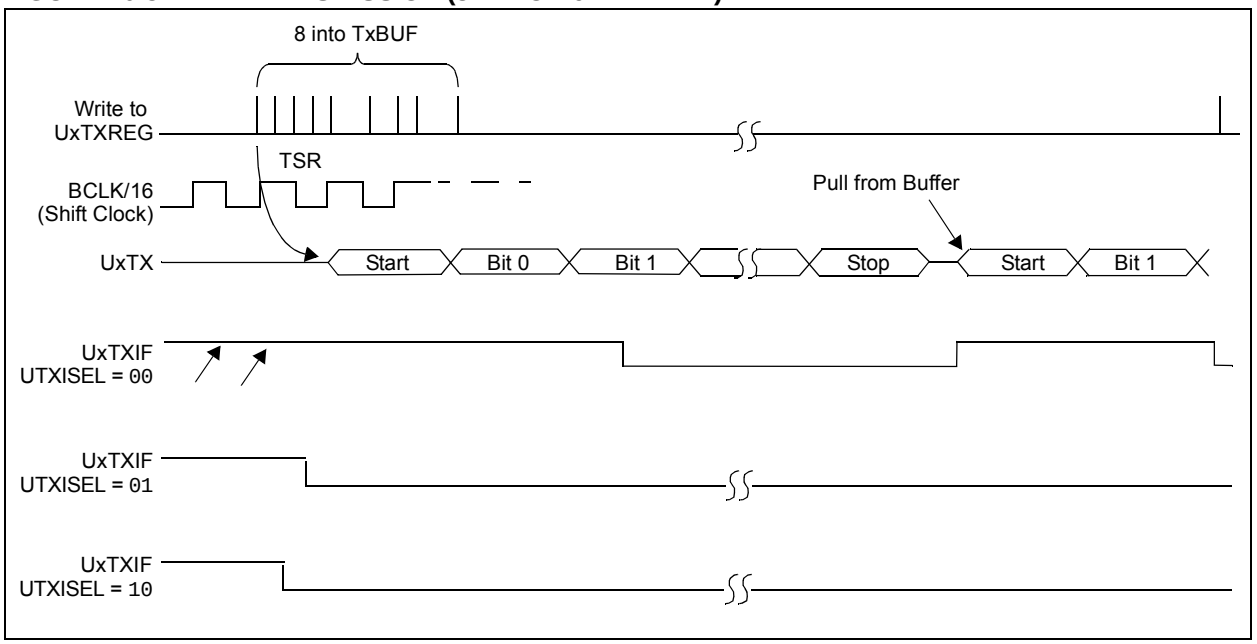


FIGURE 20-3: TRANSMISSION (8-BIT OR 9-BIT DATA)



REGISTER 22-3: RTCTIME: RTC TIME VALUE REGISTER

Bit Range	Bit 31/23/15/7	Bit 30/22/14/6	Bit 29/21/13/5	Bit 28/20/12/4	Bit 27/19/11/3	Bit 26/18/10/2	Bit 25/17/9/1	Bit 24/16/8/0
31:24	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	HR10<3:0>				HR01<3:0>			
23:16	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	MIN10<3:0>				MIN01<3:0>			
15:8	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x	R/W-x
	SEC10<3:0>				SEC01<3:0>			
7:0	U-0	U-0	U-0	U-0	U-0	U-0	U-0	U-0
	—	—	—	—	—	—	—	—

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 31-28 **HR10<3:0>:** Binary-Coded Decimal Value of Hours bits, 10s place digits; contains a value from 0 to 2

bit 27-24 **HR01<3:0>:** Binary-Coded Decimal Value of Hours bits, 1s place digit; contains a value from 0 to 9

bit 23-20 **MIN10<3:0>:** Binary-Coded Decimal Value of Minutes bits, 10s place digits; contains a value from 0 to 5

bit 19-16 **MIN01<3:0>:** Binary-Coded Decimal Value of Minutes bits, 1s place digit; contains a value from 0 to 9

bit 15-12 **SEC10<3:0>:** Binary-Coded Decimal Value of Seconds bits, 10s place digits; contains a value from 0 to 5

bit 11-8 **SEC01<3:0>:** Binary-Coded Decimal Value of Seconds bits, 1s place digit; contains a value from 0 to 9

bit 7-0 **Unimplemented:** Read as '0'

Note: This register is only writable when RTCWREN = 1 (RTCCON<3>).

30.6 MPLAB X SIM Software Simulator

The MPLAB X SIM Software Simulator allows code development in a PC-hosted environment by simulating the PIC MCUs and dsPIC DSCs on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a comprehensive stimulus controller. Registers can be logged to files for further run-time analysis. The trace buffer and logic analyzer display extend the power of the simulator to record and track program execution, actions on I/O, most peripherals and internal registers.

The MPLAB X SIM Software Simulator fully supports symbolic debugging using the MPLAB XC Compilers, and the MPASM and MPLAB Assemblers. The software simulator offers the flexibility to develop and debug code outside of the hardware laboratory environment, making it an excellent, economical software development tool.

30.7 MPLAB REAL ICE In-Circuit Emulator System

The MPLAB REAL ICE In-Circuit Emulator System is Microchip's next generation high-speed emulator for Microchip Flash DSC and MCU devices. It debugs and programs all 8, 16 and 32-bit MCU, and DSC devices with the easy-to-use, powerful graphical user interface of the MPLAB X IDE.

The emulator is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with either a connector compatible with in-circuit debugger systems (RJ-11) or with the new high-speed, noise tolerant, Low-Voltage Differential Signal (LVDS) interconnection (CAT5).

The emulator is field upgradable through future firmware downloads in MPLAB X IDE. MPLAB REAL ICE offers significant advantages over competitive emulators including full-speed emulation, run-time variable watches, trace analysis, complex breakpoints, logic probes, a ruggedized probe interface and long (up to three meters) interconnection cables.

30.8 MPLAB ICD 3 In-Circuit Debugger System

The MPLAB ICD 3 In-Circuit Debugger System is Microchip's most cost-effective, high-speed hardware debugger/programmer for Microchip Flash DSC and MCU devices. It debugs and programs PIC Flash microcontrollers and dsPIC DSCs with the powerful, yet easy-to-use graphical user interface of the MPLAB IDE.

The MPLAB ICD 3 In-Circuit Debugger probe is connected to the design engineer's PC using a high-speed USB 2.0 interface and is connected to the target with a connector compatible with the MPLAB ICD 2 or MPLAB REAL ICE systems (RJ-11). MPLAB ICD 3 supports all MPLAB ICD 2 headers.

30.9 PICkit 3 In-Circuit Debugger/ Programmer

The MPLAB PICkit 3 allows debugging and programming of PIC and dsPIC Flash microcontrollers at a most affordable price point using the powerful graphical user interface of the MPLAB IDE. The MPLAB PICkit 3 is connected to the design engineer's PC using a full-speed USB interface and can be connected to the target via a Microchip debug (RJ-11) connector (compatible with MPLAB ICD 3 and MPLAB REAL ICE). The connector uses two device I/O pins and the Reset line to implement in-circuit debugging and In-Circuit Serial Programming™ (ICSP™).

30.10 MPLAB PM3 Device Programmer

The MPLAB PM3 Device Programmer is a universal, CE compliant device programmer with programmable voltage verification at V_{DDMIN} and V_{DDMAX} for maximum reliability. It features a large LCD display (128 x 64) for menus and error messages, and a modular, detachable socket assembly to support various package types. The ICSP cable assembly is included as a standard item. In Stand-Alone mode, the MPLAB PM3 Device Programmer can read, verify and program PIC devices without a PC connection. It can also set code protection in this mode. The MPLAB PM3 connects to the host PC via an RS-232 or USB cable. The MPLAB PM3 has high-speed communications and optimized algorithms for quick programming of large memory devices, and incorporates an MMC card for file storage and data applications.

30.11 Demonstration/Development Boards, Evaluation Kits, and Starter Kits

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM™ and dsPICDEM™ demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ® security ICs, CAN, IrDA®, PowerSmart battery management, SEEVAL® evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Also available are starter kits that contain everything needed to experience the specified device. This usually includes a single application and debug capability, all on one board.

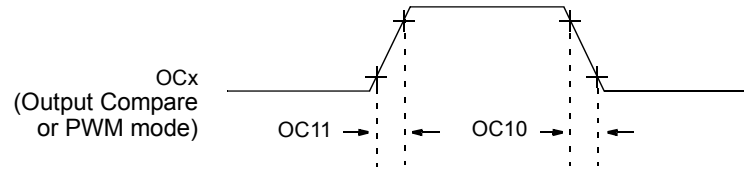
Check the Microchip web page (www.microchip.com) for the complete list of demonstration, development and evaluation kits.

30.12 Third-Party Development Tools

Microchip also offers a great collection of tools from third-party vendors. These tools are carefully selected to offer good value and unique functionality.

- Device Programmers and Gang Programmers from companies, such as SoftLog and CCS
- Software Tools from companies, such as Gimpel and Trace Systems
- Protocol Analyzers from companies, such as Saleae and Total Phase
- Demonstration Boards from companies, such as MikroElektronika, Digilent® and Olimex
- Embedded Ethernet Solutions from companies, such as EZ Web Lynx, WIZnet and IPLogika®

FIGURE 31-8: OUTPUT COMPARE MODULE (OCx) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

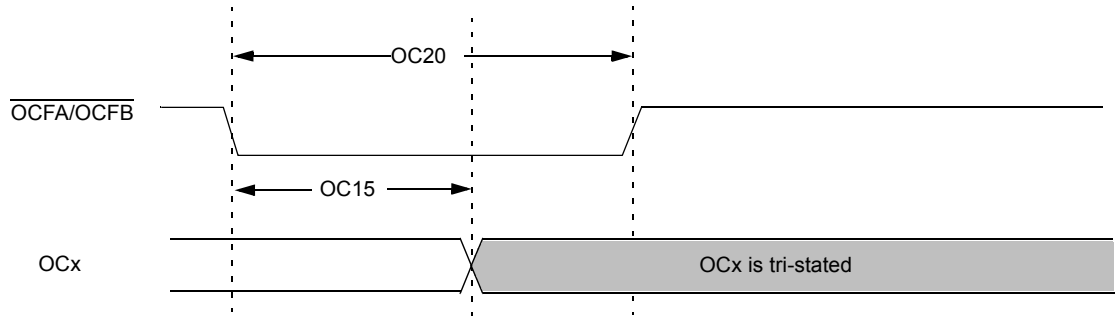
TABLE 31-27: OUTPUT COMPARE MODULE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
OC10	TccF	OCx Output Fall Time	—	—	—	ns	See parameter DO32
OC11	TccR	OCx Output Rise Time	—	—	—	ns	See parameter DO31

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-9: OCx/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

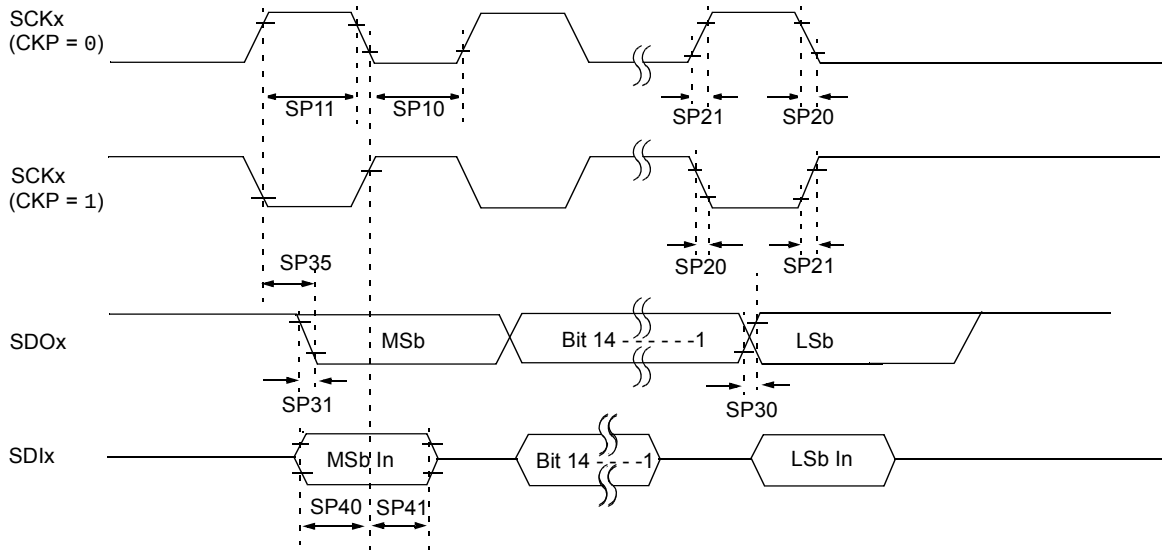
TABLE 31-28: SIMPLE OCx/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	TFD	Fault Input to PWM I/O Change	—	—	50	ns	—
OC20	TFLT	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 31-10: SPIx MODULE MASTER MODE (CKE = 0) TIMING CHARACTERISTICS



Note: Refer to Figure 31-1 for load conditions.

TABLE 31-29: SPIx MASTER MODE (CKE = 0) TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature 0°C ≤ TA ≤ +70°C for Commercial -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP10	TscL	SCKx Output Low Time **(Note 3)**	Tsck/2	—	—	ns	—
SP11	TscH	SCKx Output High Time **(Note 3)**	Tsck/2	—	—	ns	—
SP20	TscF	SCKx Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP21	TscR	SCKx Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP30	TdoF	SDOx Data Output Fall Time **(Note 4)**	—	—	—	ns	See parameter DO32
SP31	TdoR	SDOx Data Output Rise Time **(Note 4)**	—	—	—	ns	See parameter DO31
SP35	TscH2doV, TscL2doV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP40	TdiV2scH, TdiV2scL	Setup Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—
SP41	TscH2diL, TscL2diL	Hold Time of SDIx Data Input to SCKx Edge	10	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

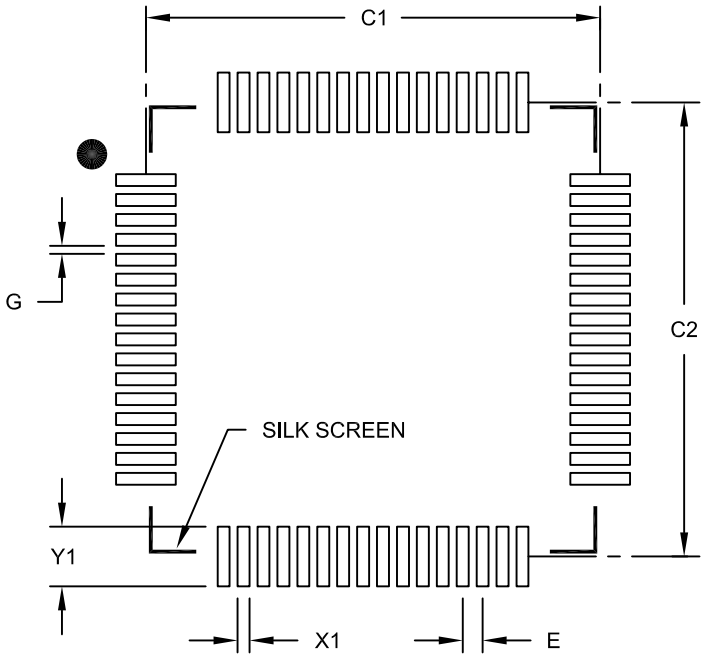
2: Data in "Typical" column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

64-Lead Plastic Thin Quad Flatpack (PT) 10x10x1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E		0.50 BSC	
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X64)	X1			0.30
Contact Pad Length (X64)	Y1			1.50
Distance Between Pads	G	0.20		

Notes:

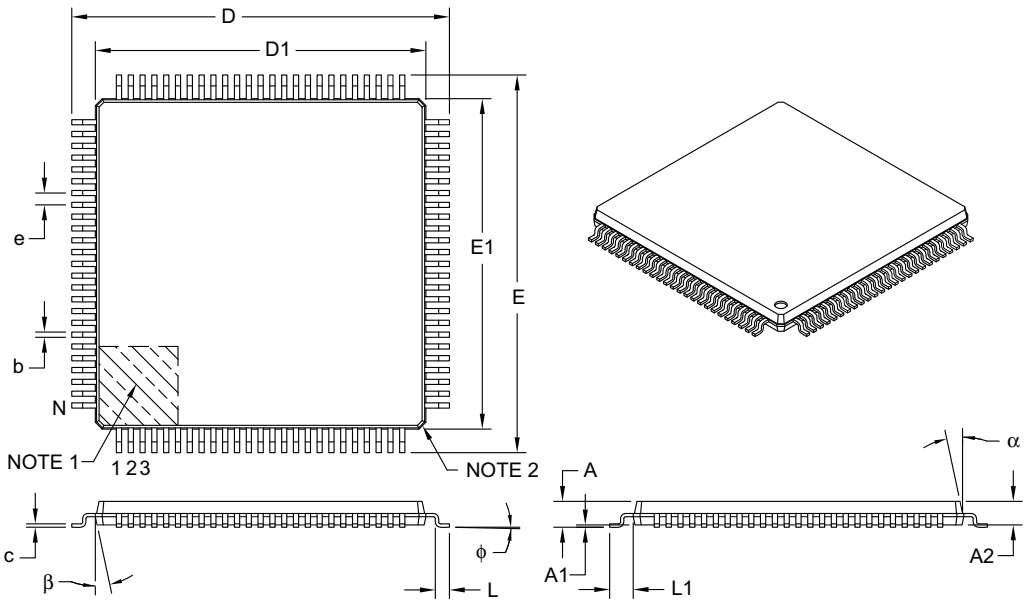
1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2085B

100-Lead Plastic Thin Quad Flatpack (PF) – 14x14x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.50 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		16.00 BSC	
Overall Length	D		16.00 BSC	
Molded Package Width	E1		14.00 BSC	
Molded Package Length	D1		14.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

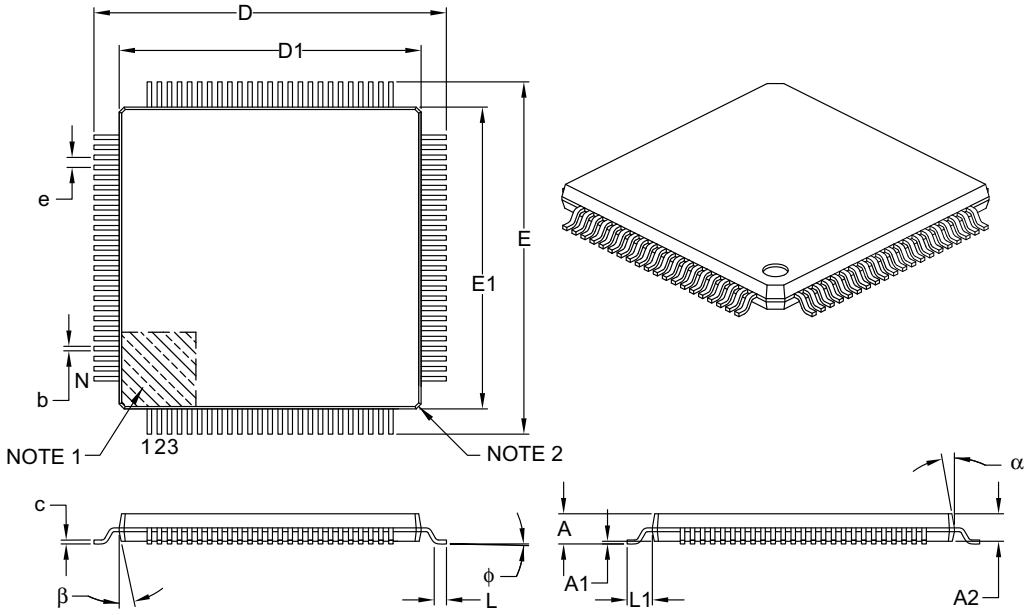
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.
REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-110B

100-Lead Plastic Thin Quad Flatpack (PT) – 12x12x1 mm Body, 2.00 mm [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		100	
Lead Pitch	e		0.40 BSC	
Overall Height	A	–	–	1.20
Molded Package Thickness	A2	0.95	1.00	1.05
Standoff	A1	0.05	–	0.15
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		14.00 BSC	
Overall Length	D		14.00 BSC	
Molded Package Width	E1		12.00 BSC	
Molded Package Length	D1		12.00 BSC	
Lead Thickness	c	0.09	–	0.20
Lead Width	b	0.13	0.18	0.23
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25 mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M.

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-100B

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELOQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

QUALITY MANAGEMENT SYSTEM
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